
DesignConEast 2005

Track 4: Power and Packaging (4-WA1)

Design of a Low-Power Differential Repeater Using Low-Voltage Swing and Charge Recycling

Authors:

**Brock J. LaMeres,
University of Colorado /**



Agilent Technologies

**Sunil P. Khatri
Texas A&M University**

Problem Statement

- **Power is the largest problem facing IC/SoC designers**
- **On-chip trace delay limits performance in DSM**
 - 1) **Repeaters are used to reduce delay**
 - 2) **Repeaters add power**

Agenda

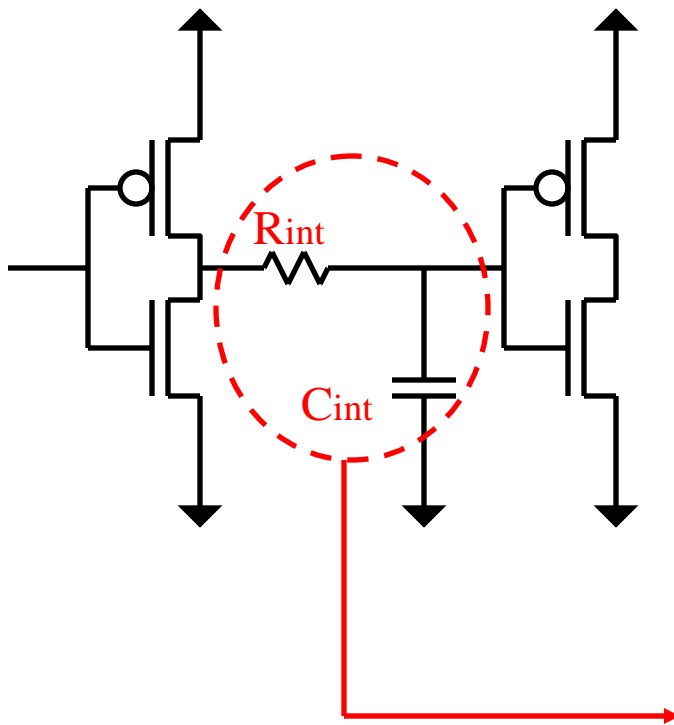
1) Problem Motivation

2) Proposed Solution

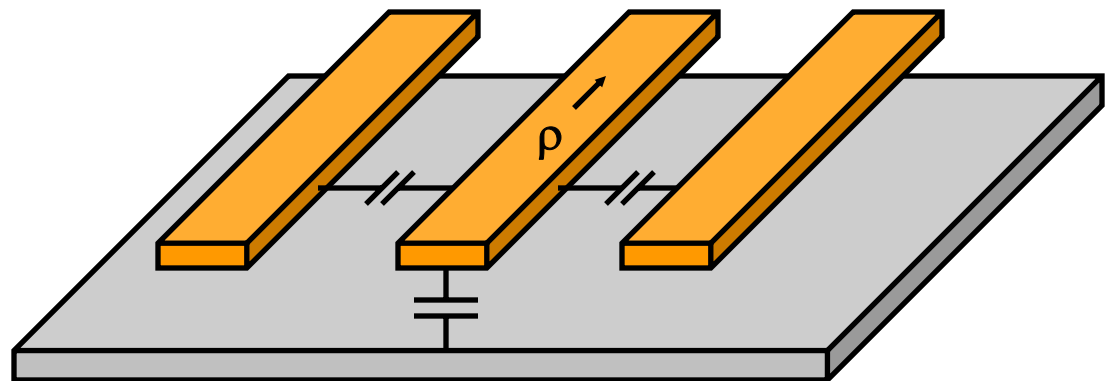
3) Simulation Results

Problem Motivation

RC Trace Delay

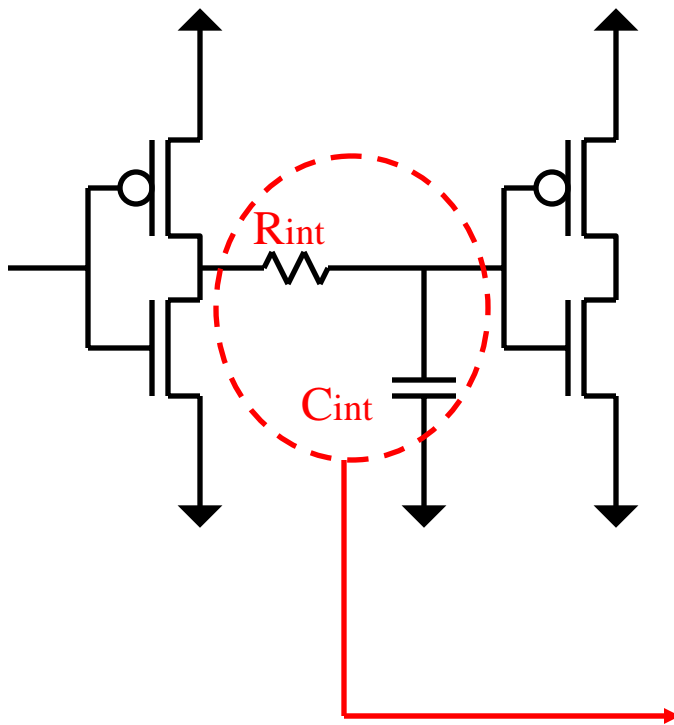


$$t_{RC} = (0.69) \cdot RC$$



Problem Motivation

RC Trace Delay

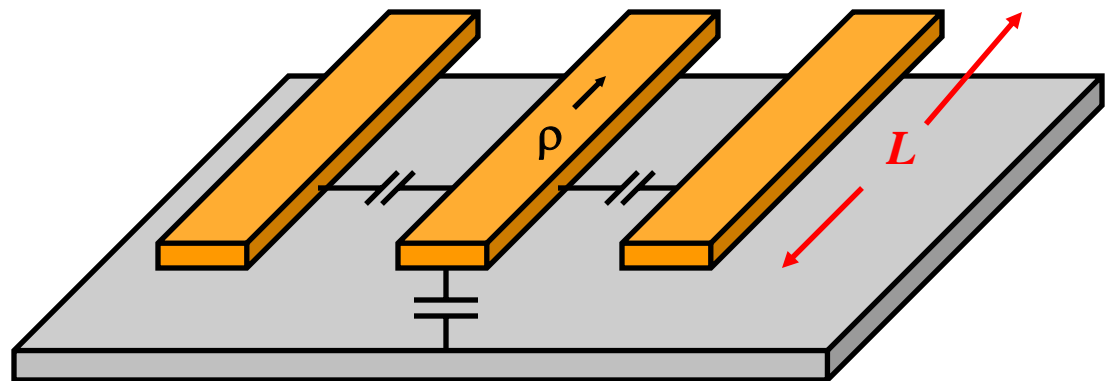


$$R = \frac{\rho L}{A} \propto L$$

$$C = \frac{\epsilon \cdot W \cdot L}{t_{ox}} \propto L$$

$$t_{RC} \propto L^2$$

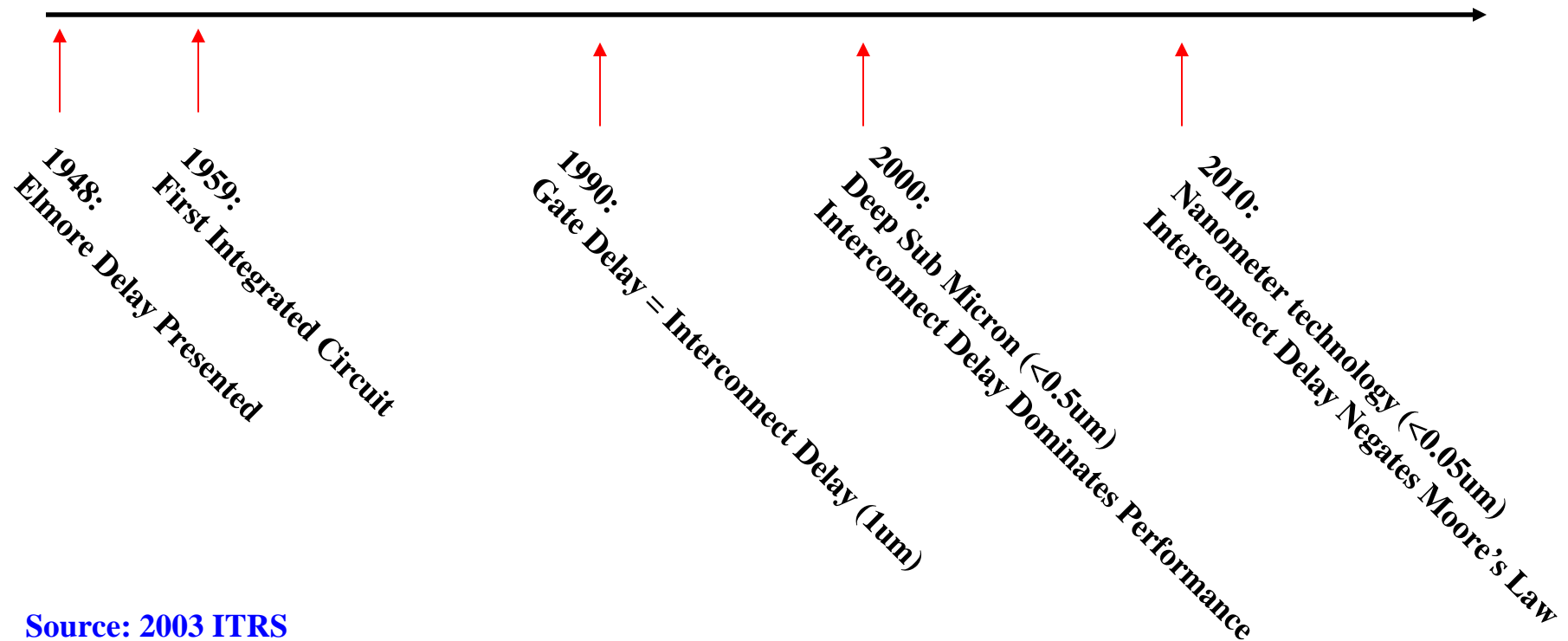
Quadratic Increase



Problem Motivation

Interconnect Dominates DSM Performance

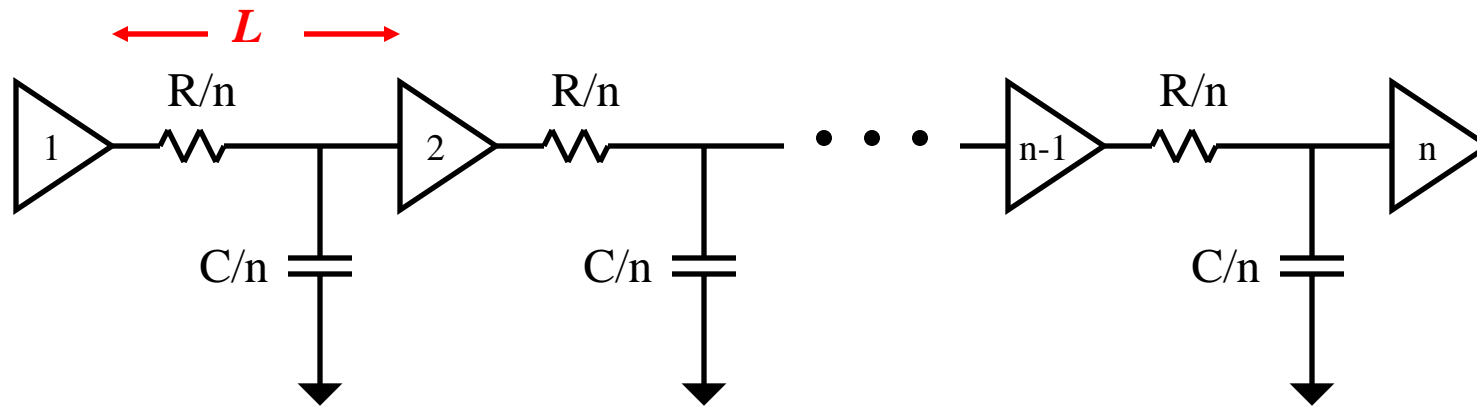
Today



Source: 2003 ITRS

Problem Motivation

Standard Solution : “Repeater Insertion”



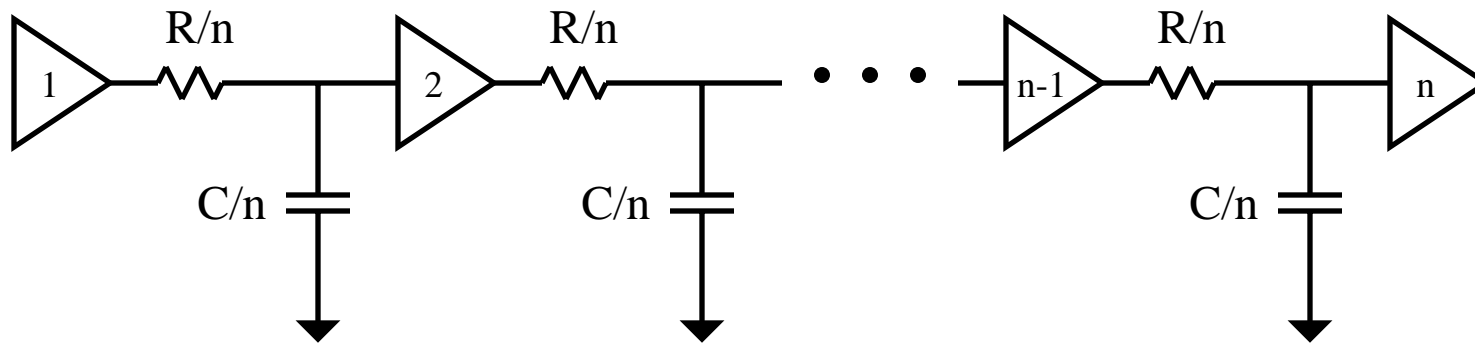
- Break line into smaller segments: $(L \rightarrow 0)$

- Optimal sizing when: $t_{buf} = t_{RC}$

- Linear dependence: $t_{delay} \propto L$

Problem Motivation

Repeaters Add Power



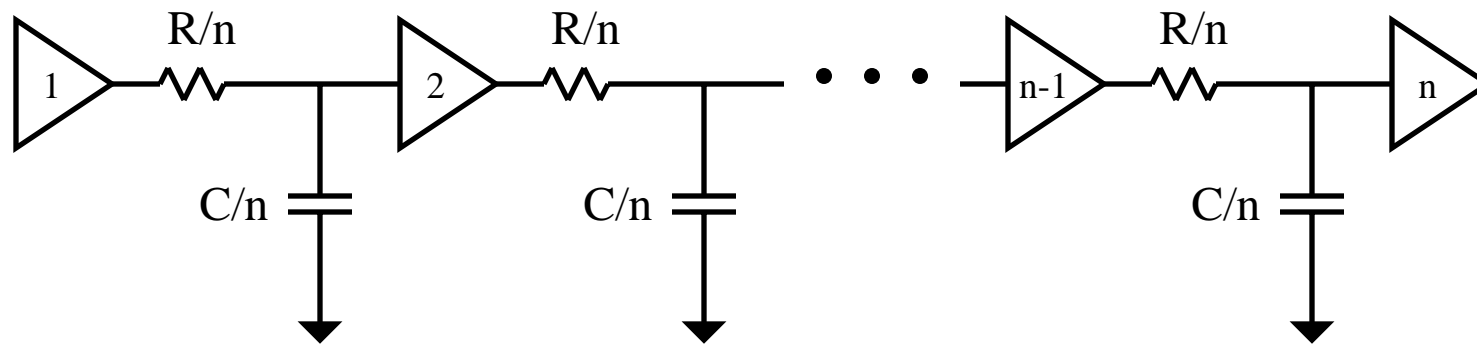
$$P_{dynamic} = C \cdot V_{swing}^2 \cdot f$$

$$P_{short-circuit} = I_{sat} \cdot V_{DD} \cdot f$$

Power \propto (# of Repeaters)

Problem Motivation

Repeater Power Scaling Isn't Realistic

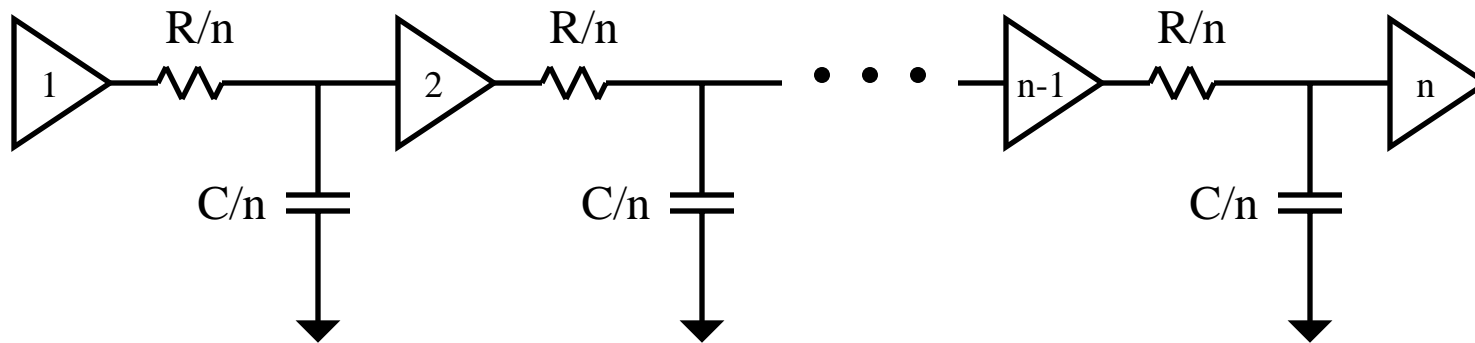


2003 ITRS Prediction:

- at 50nm, global interconnect will consume 40% of power in VLSI
- 0.25um μP : 50,000 repeaters : 8 Watts
- 70nm μP : 700,000 repeaters : 60 Watts

Problem Motivation

Need to Reduce Power

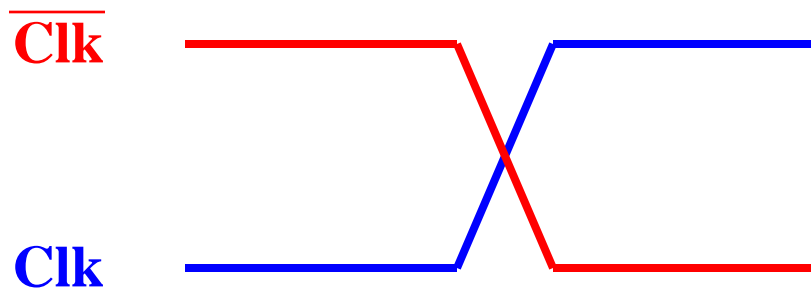


- **Need techniques to reduce power of repeater scheme**
- **A small decrease in delay is acceptable**
- **Net improvement in PDP is the goal**

Proposed Solution

Current Trends

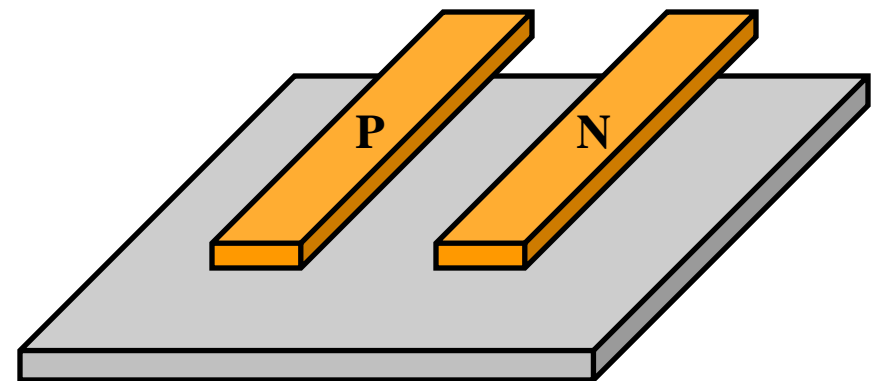
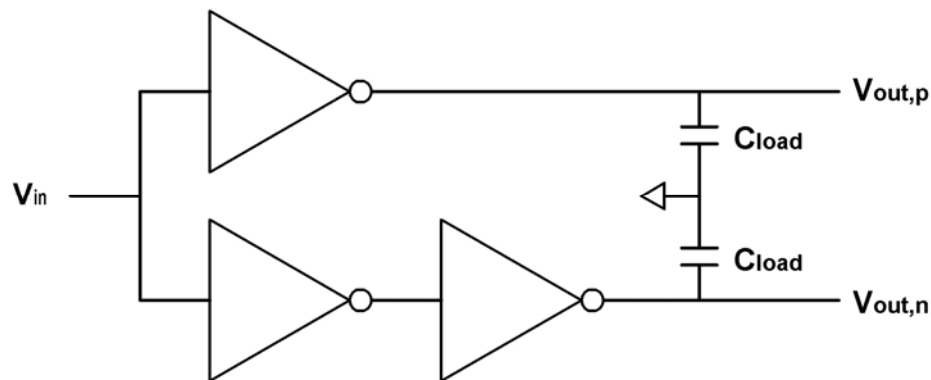
- **Differential signaling on clock traces for Noise Immunity**
 - Well Suited for Low-Voltage Output Swing
 - Well Suited for Charge Sharing



Proposed Solution

Differential Signaling

- Complimentary Outputs for VLSI CMOS
- Receiver Performs ($\text{CLK}-\overline{\text{CLK}}$) which rejects coupled noise
- Receiver Performs ($\text{CLK}-\overline{\text{CLK}}$) which doubles effective amplitude



Proposed Solution

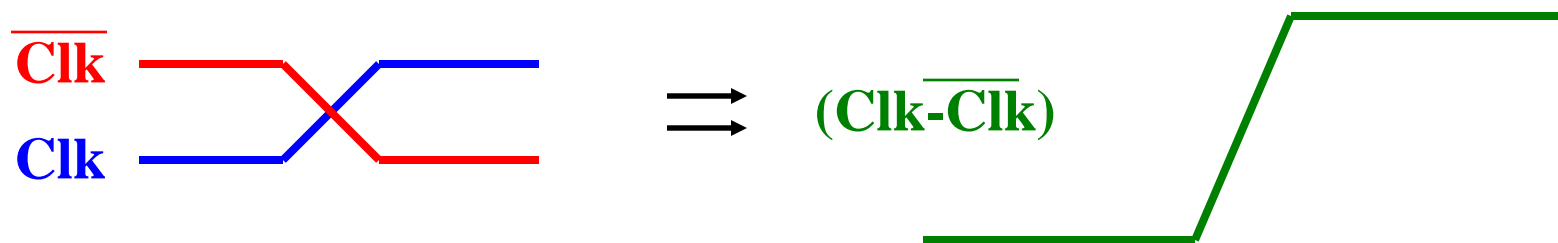
Low-Voltage Swing Outputs

- Reducing Output Swing Reduces Power

$$P_{dynamic} = C \cdot V_{swing}^2 \cdot f$$

**Quadratic
Decrease!!!**

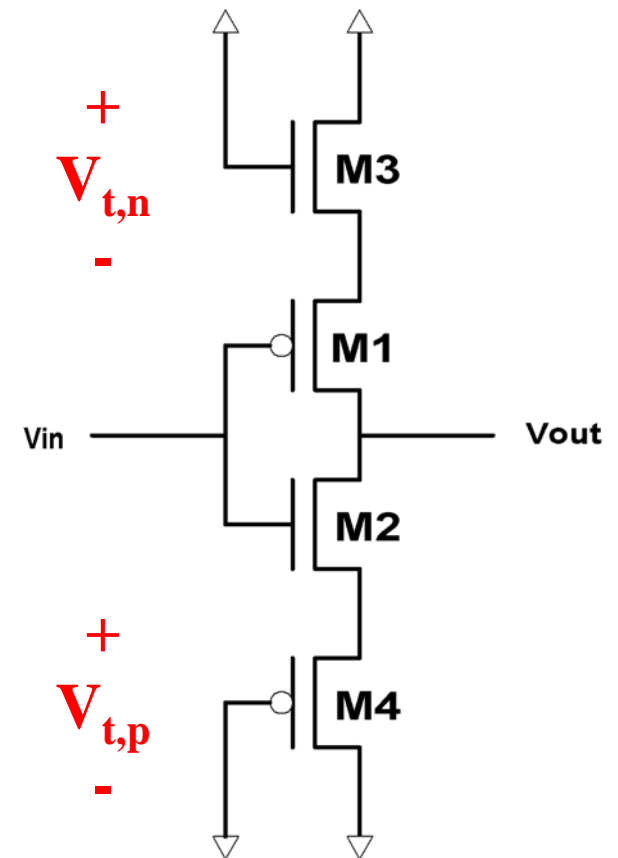
- Differential Signaling has extra margin to accommodate this



Proposed Solution

Low-Voltage Swing Outputs

- Typical CMOS swings from V_{SS} to V_{DD}
- Insert V_t drops between supplies to reduce output swing



Proposed Solution

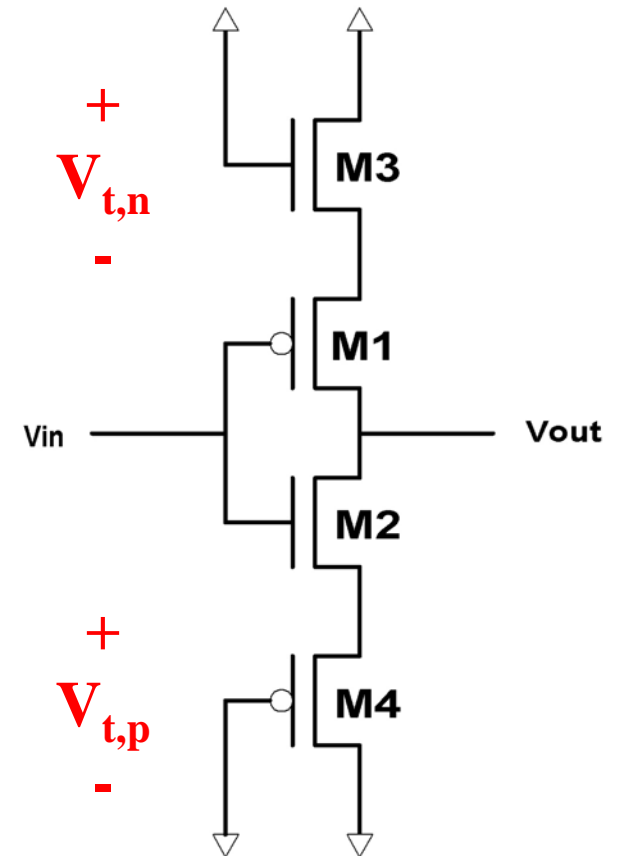
Low-Voltage Swing Outputs

- The reduced output swing is:

$$V_{LV-swing} = V_{DD} - V_{t,n} - |V_{t,p}|$$

- The reduced power is:

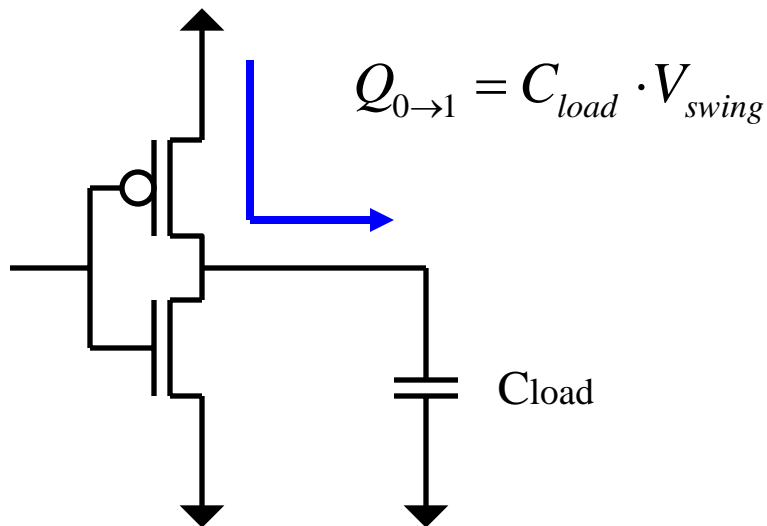
$$P_{dynamic} = C \cdot V_{LV-swing}^2 \cdot f$$



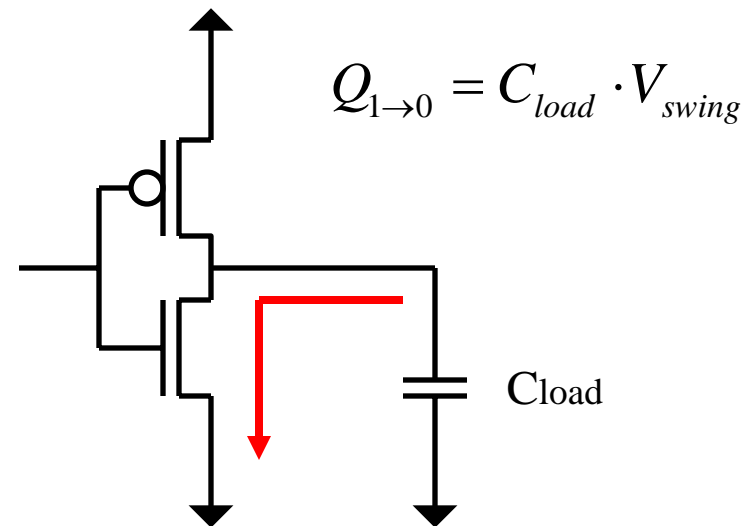
Proposed Solution

Charge Recycling

- Typical CMOS charges output from supply



0 → 1 Transition

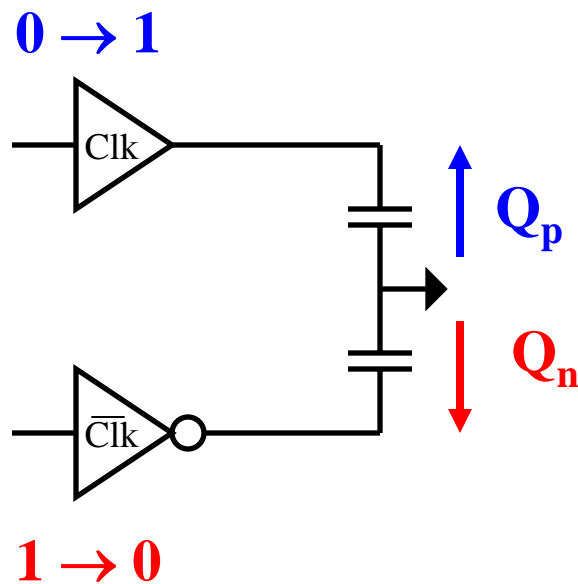


1 → 0 Transition

Proposed Solution

Charge Recycling

- The Symmetry of Differential Signaling can be exploited

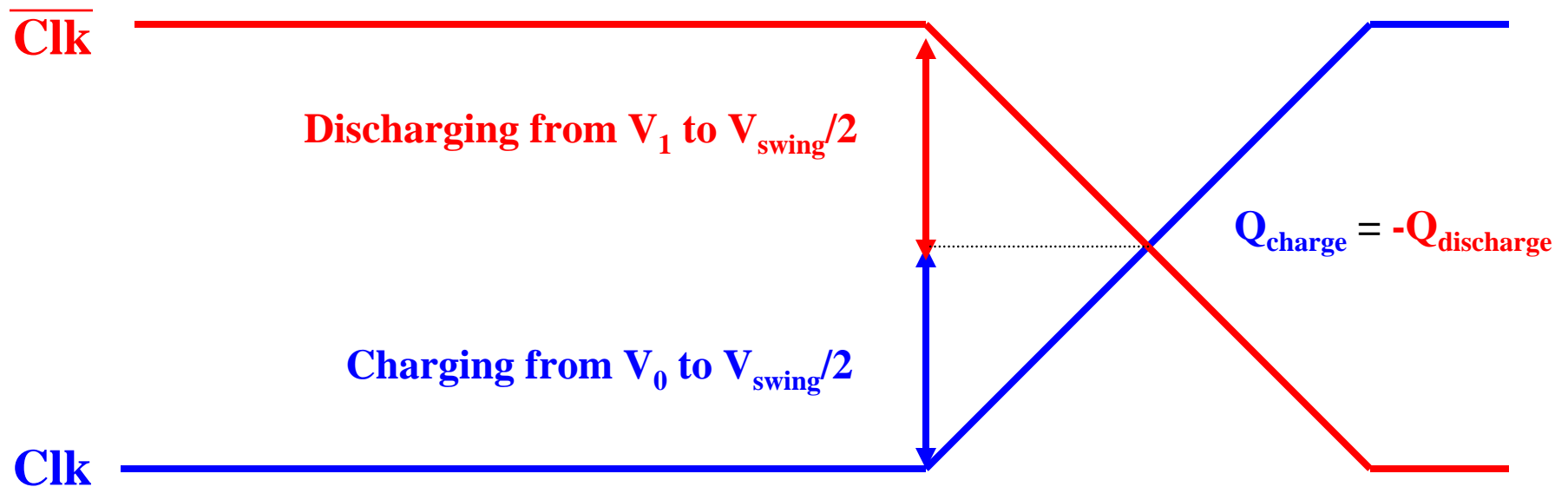


One Driver is always **charging**
while the other is **discharging**

Proposed Solution

Charge Recycling

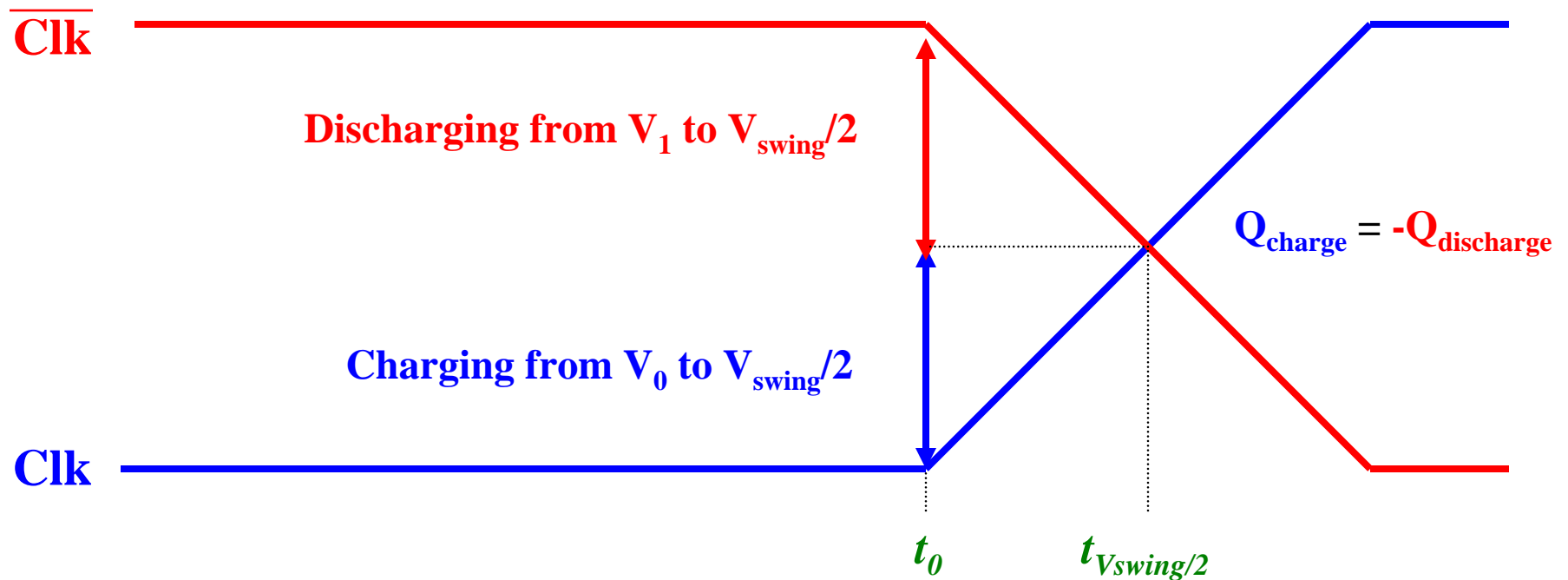
- During first half of the transition equal charge is distributed



Proposed Solution

Charge Recycling

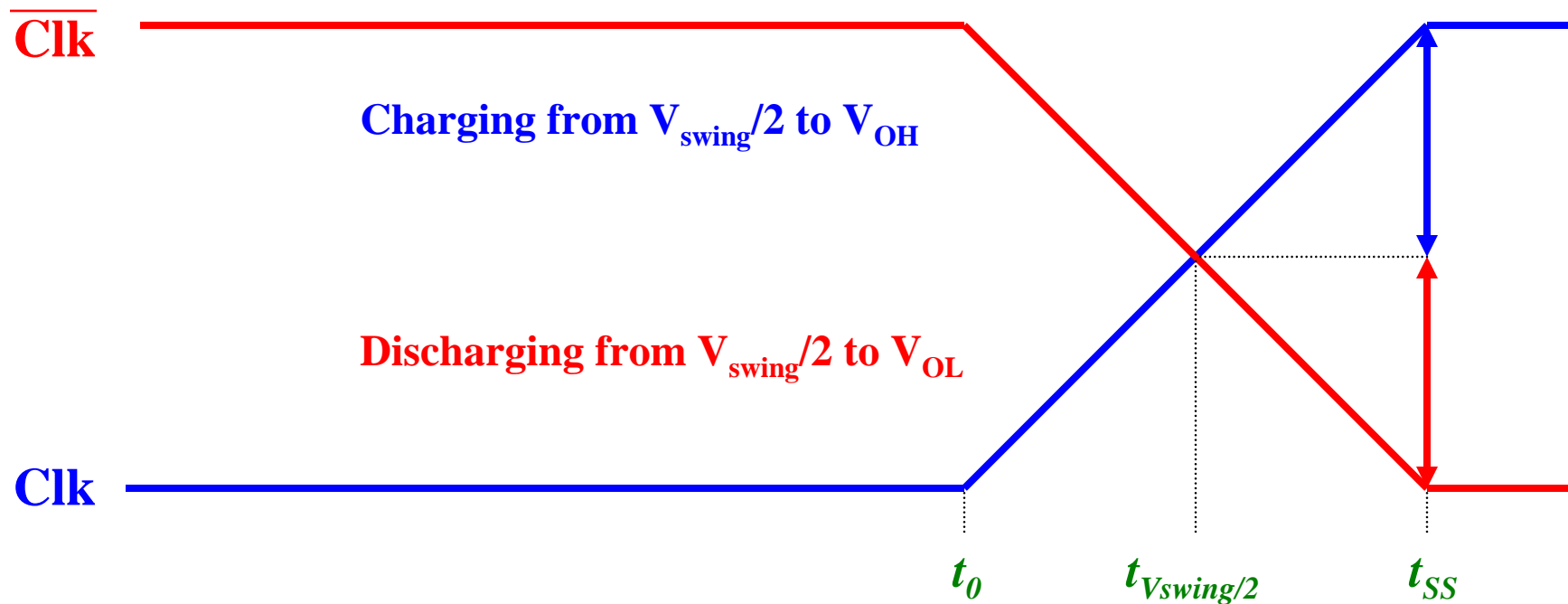
- Charge can be “Shared” between **Clk** & $\overline{\text{Clk}}$ from t_0 to $t_{V_{\text{swing}}/2}$



Proposed Solution

Charge Recycling

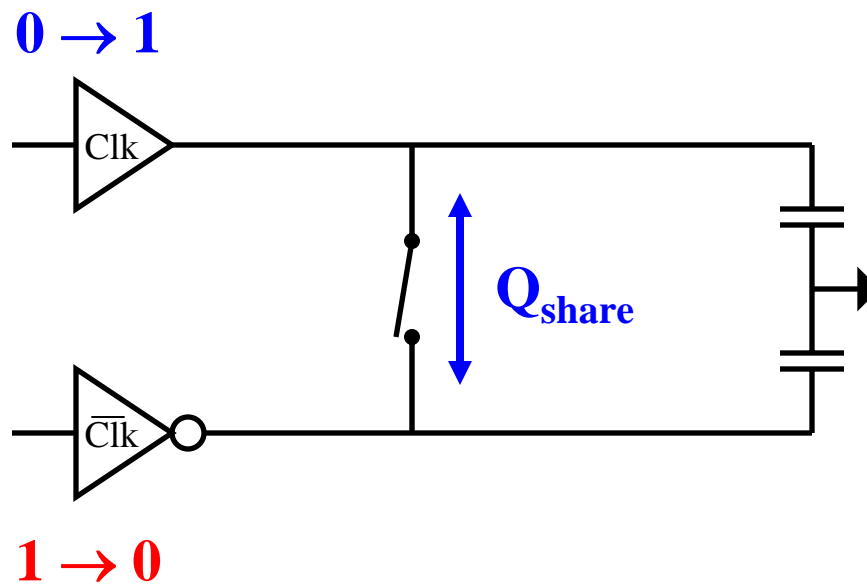
- From $t_{V_{swing}/2}$ to t_{SS} charge is provided by Supplies as usual



Proposed Solution

Charge Recycling

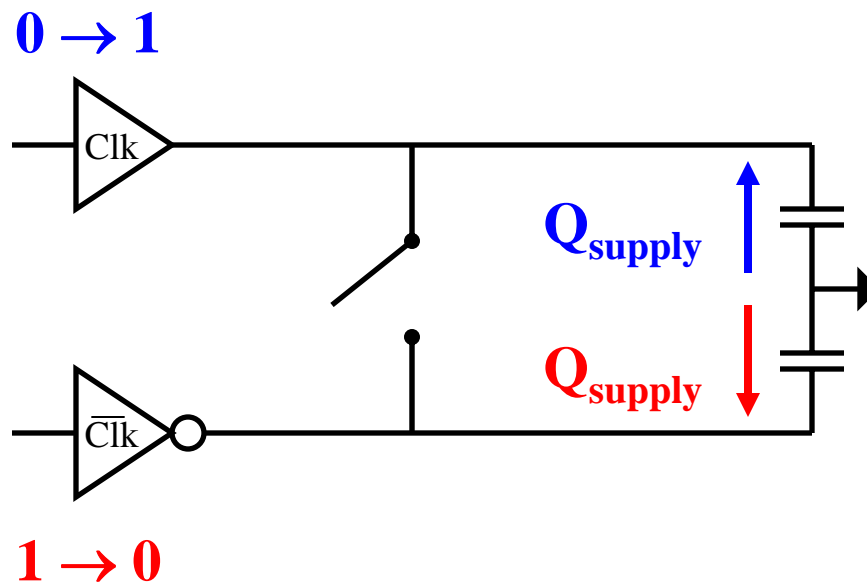
- **Clk** & **Clk** are connected from t_0 to $t_{V_{swing}/2}$



Proposed Solution

Charge Recycling

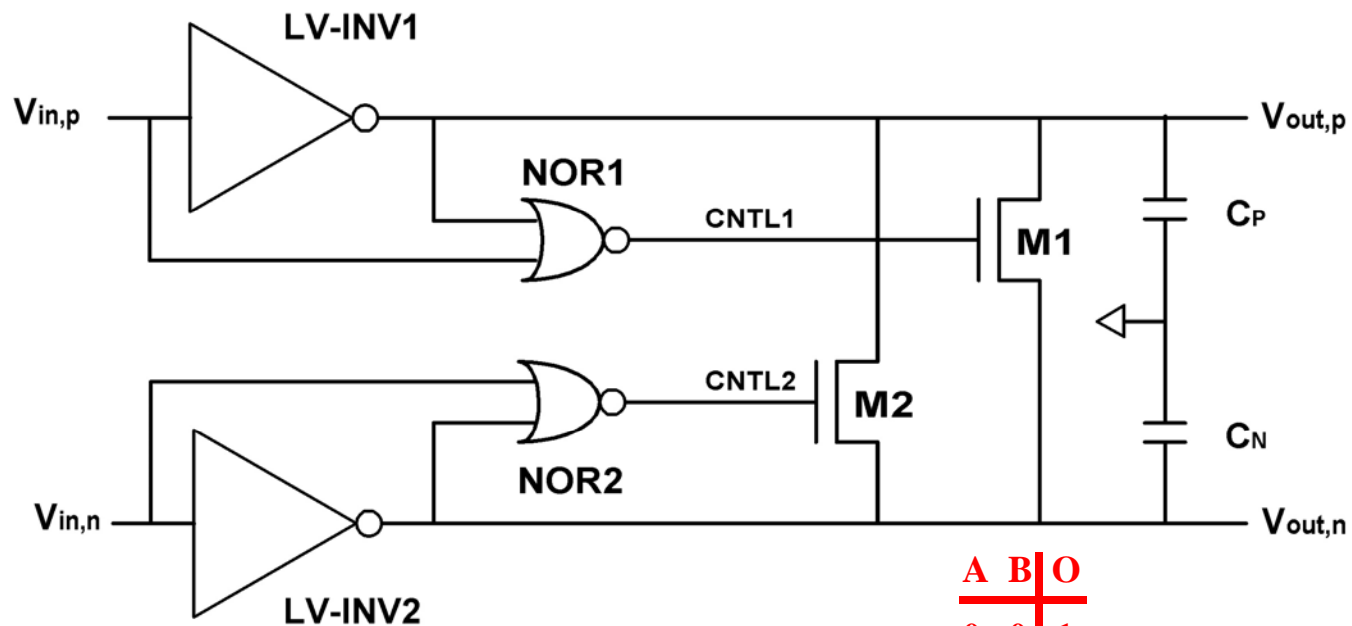
- **Clk** & **Clk** are disconnected from $t_{V_{swing}/2}$ to t_{SS}



Proposed Solution

Charge Recycling

- **Circuit Description**

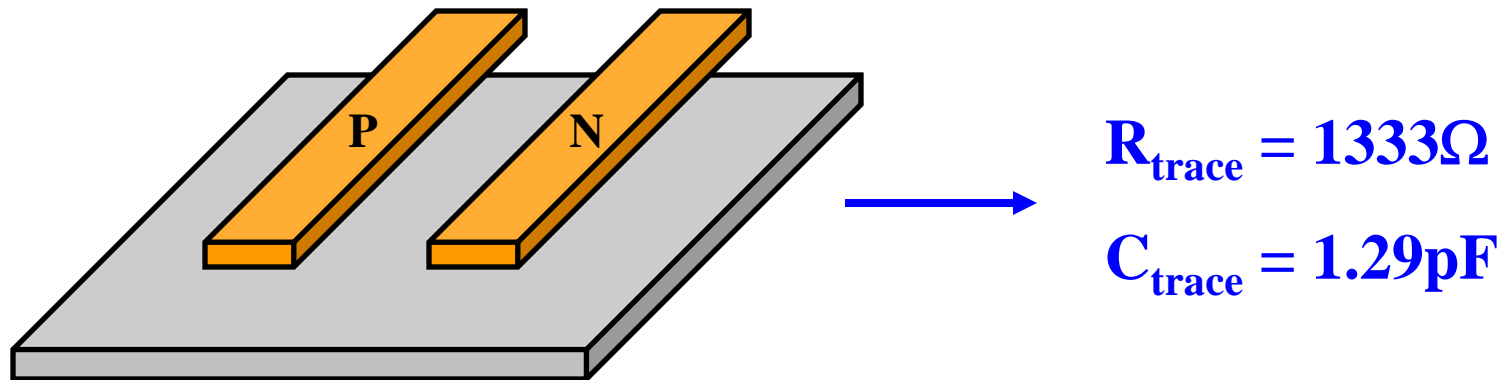


A	B	O
0	0	1
0	1	0
1	0	0
1	1	0

Simulation Results

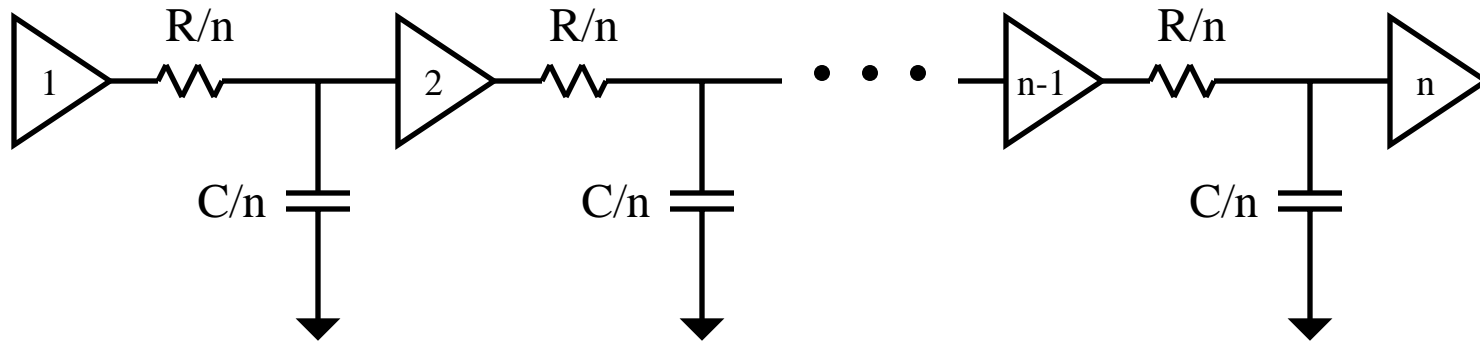
Trace Modeling

- **BSIM 0.1um Process (BPTM)**
- **1cm Length**
- **Metal 3**



Simulation Results

Repeater Design



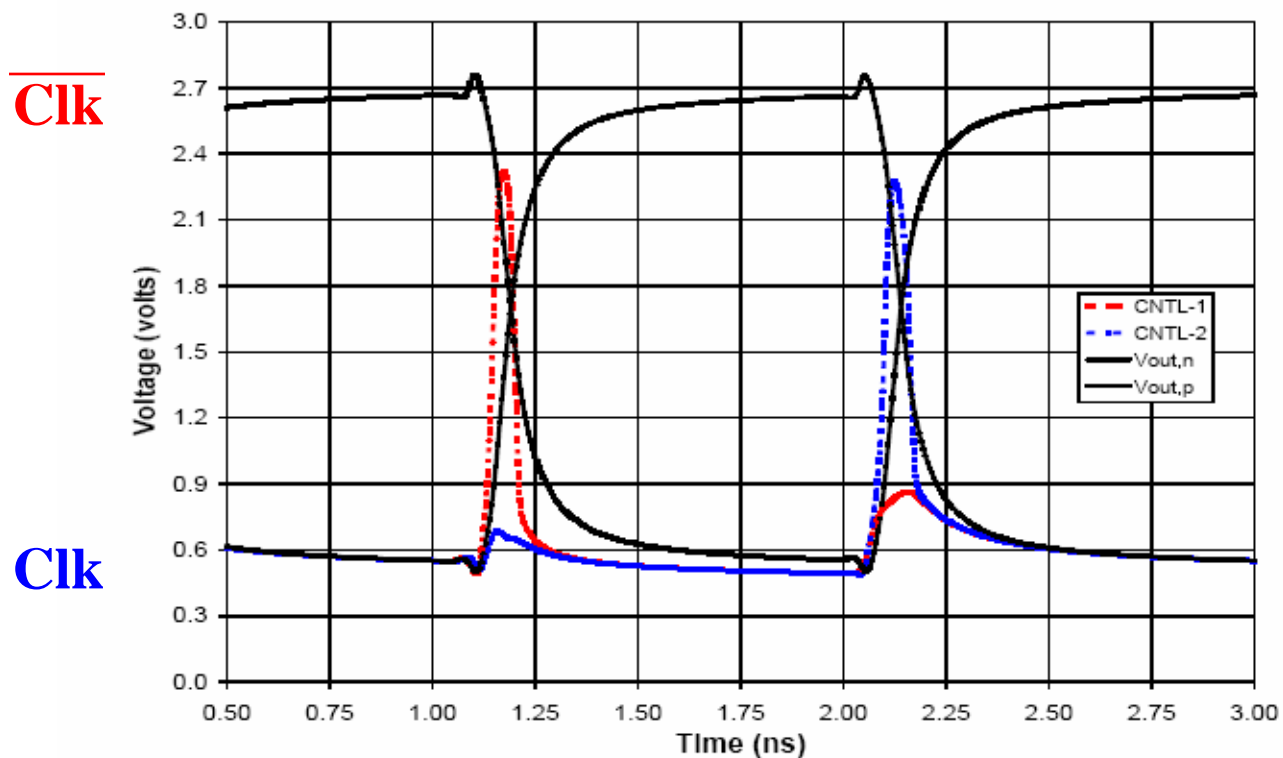
Using Optimal Sizing:

- **Full-Swing Repeater:** 15
- **Low-Voltage Repeater:** 9
- **Low-Voltage Charge Recycling Repeater:** 9

Simulation Results

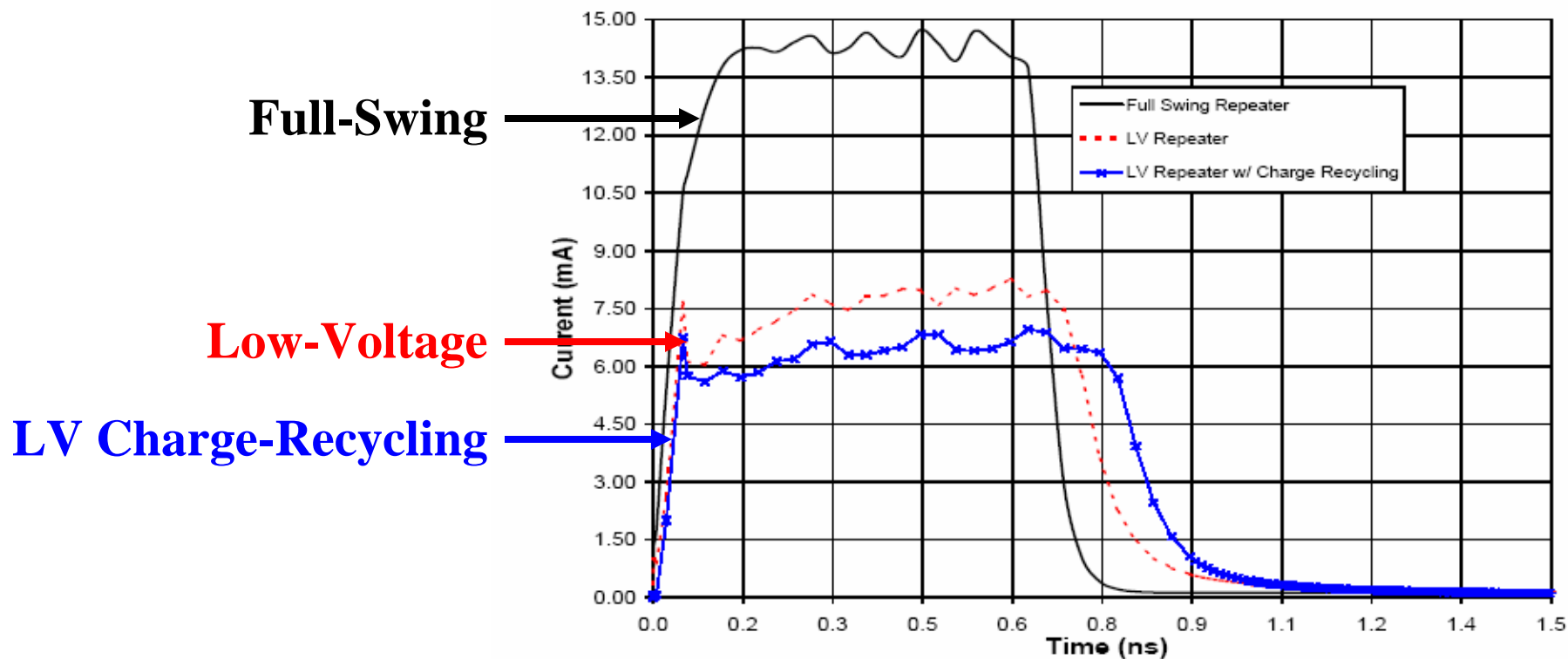
Circuit Operation

- Circuit Operation



Simulation Results

Current Profile vs. Time



Simulation Results

Performance

Both Improve PDP

Circuit	Figures of Merit			Improvement		
	Delay (ps)	Power (mV)	PDP (ps · mV)	Delay (%)	Power (%)	PDP (%)
Full-Swing Repeater	639	12.06	7.71	-	-	-
Low-Voltage Repeater	699	7.54	5.27	-9	37	32
Low-Voltage Charge Recycling Repeater	774	6.92	5.36	-21	43	31

- **Lowest Delay** = **Full-Swing Repeater**
- **Lowest PDP** = **Low-Voltage Repeater**
(32% improvement)
- **Lowest Power** = **Low-Voltage Charge Recycling Repeater**
(43% improvement)

Implementation Details

Suggested Use

- **On-Chip Metal 3 or Greater**

Not Suggested

- **On-Chip Metal 1 or 2**
(too much resistance, acts distributed)
- **Off-Chip**
(too much inductance, acts distributed)

Implementation Details

Sizing

Circuit	Section	Transistor	Size
Full-Swing Repeater	INV	NMOS	2.5/0.1
		PMOS	8.0/0.1
Low-Voltage Repeater	INV	NMOS	5.0/0.1
		PMOS	16.0/0.1
	V_t Drop	NMOS	25/0.1
		PMOS	80/0.1
Low-Voltage Charge Recycling Repeater	INV	NMOS	5.0/0.1
		PMOS	16.0/0.1
	V_t Drop	NMOS	25/0.1
		PMOS	80/0.1
	NOR	NMOS	0.2/0.1
		PMOS	0.8/0.1
CS	NMOS	0.2/0.1	

- Low Resistance
- Negligible Capacitance

< (20%) τ_{load}

Summary

Trends

- **Power and Delay are major problems in DSM**
- **Repeaters are expected to dominate power**
- **Differential signaling is being used for noise immunity on clocks**

Proposed Technique

- **Low-Voltage Swing enabled by differential signaling**
- **Charge Recycling enabled by differential signaling**
- **Suffer small delay penalty for decreased power (PDP ↑)**

Questions?